Amendments to the Claims

The listing of claims will replace all prior versions, and listings of claims in the application.

1. (*previously presented*) An integrated circuit, comprising:

a fuse corner pad located at a first corner of the integrated circuit,

wherein said fuse corner pad includes a fuse contact coupled to said fuse corner pad, and

wherein said fuse corner pad is incapable of being bonded to an external electrical connection.

2. (*original*) The integrated circuit of claim 1, further comprising:

a fuse element connected to said fuse contact.

3. (*original*) The integrated circuit of claim 2, wherein said fuse element is adapted to adjust a transmitting waveform to comply with a predefined parameter.

4. (*original*) The integrated circuit of claim 2, wherein said fuse element is adapted to communicate a state of said fuse element, said state identifying the integrated circuit.

5. (*original*) The integrated circuit of claim 1, wherein said fuse contact is capable of being probed without being bonded to an external connection.

6. (*original*) The integrated circuit of claim 1, further comprising:

an auxiliary pad coupled to said fuse corner pad.

7. (*original*) The integrated circuit of claim 6, wherein said auxiliary pad is a second fuse contact.

8. (*original*) The integrated circuit of claim 6, wherein said auxiliary pad communicates signals for circuit testing.

9. (*Currently amended*) A fuse corner pad located at a corner of a semiconductor die, comprising:

a fuse contact coupled to the fuse corner pad;

wherein said fuse corner pad is incapable of being bonded to an external electrical connection; and

a fuse element connected to said fuse contact.

10. (*original*) The fuse corner pad of claim 9, wherein said fuse contact is capable of being probed without being bonded to an external connection.

11. (*previously presented*) A semiconductor die, comprising:

at least one I/O pad, on the semiconductor die, for communicating signals; and

a fuse corner pad having a fuse integrated within said fuse corner pad, wherein said fuse corner pad is located at a corner of the semiconductor die, and wherein said fuse corner pad is incapable of being bonded to an external electrical connection.

12. (*original*) The semiconductor die of claim 11, wherein said fuse corner pad is capable of being probed without being bonded to an external connection.

13. (*original*) The semiconductor die of claim 11, wherein said fuse corner pad is one of four fuse corner pads, wherein each of said four fuse corner pads is located at a respective corner of the semiconductor die.

14. (*previously presented*) An integrated circuit, comprising:

a fuse corner pad located at a first corner of the integrated circuit,

wherein said fuse corner pad includes a plurality of fuse contacts coupled to said fuse corner pad, and wherein said fuse corner pad is incapable of being bonded to an external electrical connection.

15. (*original*) The integrated circuit of claim 14, wherein at least one of said plurality of fuse contacts is connected to a fuse element included in the integrated circuit.